Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTIONS:**

1. **V IN (2 bond pads)**
2. **V OUT (2 bond pads)**
3. **V OUT SENSE**
4. **ADJUST**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential:**

**APPROVED BY: DK DIE SIZE .022” X .022” DATE: 10/21/21**

**MFG: KNOX THICKNESS .000” P/N: 1N3511**

**DG 10.1.2**

#### Rev B, 7/1